

Global Epoxy Die Bonding Adhesive Supply, Demand and Key Producers, 2026-2032

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Abstracts

The global Epoxy Die Bonding Adhesive market size is expected to reach \$ 2562 million by 2032, rising at a market growth of 7.7% CAGR during the forecast period (2026-2032).

In 2025, global production of epoxy die bonding adhesive is approximately 37,500 metric tons, with a global average market price of around \$39,000 per metric ton. The total global production capacity for epoxy die bonding adhesive in 2025 is approximately 67,000 metric tons. The average gross profit margin for the industry stands at 37%. Epoxy Die Bonding Adhesive is a functional adhesive material based on epoxy resin, used in semiconductor packaging processes to bond semiconductor chips with substrates, lead frames, or packaging carriers. These adhesives typically form highly cross-linked structures through thermal curing, providing excellent adhesion strength, electrical insulation, dimensional stability, and chemical resistance. They are widely used in LED packaging, power devices, integrated circuit packaging, and electronic component manufacturing. By incorporating conductive or thermally conductive fillers such as silver particles, aluminum oxide, and boron nitride, epoxy die bonding adhesives can achieve enhanced electrical conductivity, heat dissipation, and high-reliability packaging performance. With the development of Mini LED, automotive electronics, power semiconductors, and advanced packaging technologies, demand for low-stress, high-thermal-conductivity, and high-reliability epoxy die bonding adhesives continues to increase.

The upstream segment of the epoxy die bonding adhesive industry mainly includes suppliers of epoxy resins, curing agents, accelerators, functional fillers, and specialty chemical additives. Epoxy resin is the key raw material determining the fundamental performance of the adhesive, with its purity, molecular structure, and thermal stability

directly affecting bonding strength and reliability. Common functional fillers include silver particles, aluminum oxide, aluminum nitride, boron nitride, and silica, which improve electrical conductivity, thermal conductivity, and mechanical stability. Upstream suppliers require capabilities in high-purity chemical synthesis, nano-filler processing, and formulation optimization. High-end epoxy die bonding adhesives require strict material consistency and impurity control, with supply concentrated among global chemical companies and specialized electronic material manufacturers. The midstream segment of the epoxy die bonding adhesive industry includes adhesive formulation design, material modification, manufacturing, and quality testing companies. Midstream manufacturers optimize epoxy systems, curing mechanisms, and filler ratios to achieve application-specific properties such as low-temperature curing, high thermal conductivity, low shrinkage, low stress, and fast curing. Products are typically supplied in liquid adhesive, paste, or preformed film formats and customized according to requirements from LED packaging, semiconductor packaging, and power device applications. Due to strict reliability requirements in chip packaging, midstream companies must establish technical barriers through long-term customer validation, reliability testing, and process integration. International companies currently dominate high-end markets, while Asian manufacturers are accelerating localization and domestic substitution strategies. The downstream applications of epoxy die bonding adhesives mainly include LED packaging, semiconductor devices, power electronics, automotive electronics, consumer electronics, and industrial electronic equipment. Traditional LED packaging represents a mature application area, where these adhesives are mainly used for die attachment and structural fixation. With the growth of electric vehicles, intelligent driving, and high-power electronic devices, demand for highly reliable die bonding adhesives in automotive LEDs and power semiconductors continues to increase. In addition, the development of Mini LED, Micro LED, and advanced packaging technologies is driving epoxy die bonding adhesives toward lower stress, higher thermal conductivity, and precision processing capabilities. In the future, downstream demand will continue expanding around high-performance electronic devices, miniaturized packaging, and high-reliability applications.

The continuous expansion of the semiconductor industry and increasing performance requirements of electronic devices are major drivers for the growth of Epoxy Die Bonding Adhesive. As a critical material in chip attachment and semiconductor packaging processes, epoxy die bonding adhesive benefits from the growth of integrated circuits, LEDs, power devices, and electronic components. The rapid development of smartphones, 5G communication, artificial intelligence computing, automotive electronics, and IoT devices has increased demand for miniaturized, highly integrated, and reliable electronic products, encouraging adhesive technologies to

improve toward lower stress, stronger adhesion, and higher durability.

The growth of electric vehicles, electrification, and intelligent driving technologies is creating new opportunities for high-performance epoxy die bonding adhesives. Power semiconductor devices such as IGBTs, MOSFETs, and SiC devices require packaging materials with excellent thermal conductivity, high-temperature resistance, and long-term reliability. By incorporating functional fillers such as silver particles, aluminum oxide, and aluminum nitride, advanced epoxy die bonding adhesives can provide enhanced electrical, thermal, and mechanical performance, supporting demanding power electronics applications.

With the development of Mini LED, Micro LED, advanced semiconductor packaging, and chiplet technologies, die bonding materials are evolving toward higher precision, lower defect rates, and improved reliability. Future epoxy die bonding adhesives will require lower thermal expansion, reduced curing shrinkage, enhanced thermal management, and more precise dispensing performance. Low-stress epoxy systems, high-thermal-conductivity formulations, and fast-curing technologies are expected to become key development directions.

This report studies the global Epoxy Die Bonding Adhesive production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for Epoxy Die Bonding Adhesive and provides market size (US\$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of Epoxy Die Bonding Adhesive that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global Epoxy Die Bonding Adhesive total production and demand, 2021-2032, (Tons)
Global Epoxy Die Bonding Adhesive total production value, 2021-2032, (USD Million)
Global Epoxy Die Bonding Adhesive production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (Tons), (based on production site)
Global Epoxy Die Bonding Adhesive consumption by region & country, CAGR, 2021-2032 & (Tons)
U.S. VS China: Epoxy Die Bonding Adhesive domestic production, consumption, key domestic manufacturers and share
Global Epoxy Die Bonding Adhesive production by manufacturer, production, price,

value and market share 2021-2026, (USD Million) & (Tons)

Global Epoxy Die Bonding Adhesive production by Type, production, value, CAGR, 2021-2032, (USD Million) & (Tons)

Global Epoxy Die Bonding Adhesive production by Application, production, value, CAGR, 2021-2032, (USD Million) & (Tons)

This report profiles key players in the global Epoxy Die Bonding Adhesive market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Henkel, Dow Chemical, Shin-Etsu Chemical, Darbond, Earlysun Technology, Kmt Technology, Niche-Tech, Huitian Adhesive, NAMICS Corporation, Panacol, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Epoxy Die Bonding Adhesive market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$ Millions), volume (production, consumption) & (Tons) and average price (US\$/Ton) by manufacturer, by Type, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

Global Epoxy Die Bonding Adhesive Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global Epoxy Die Bonding Adhesive Market, Segmentation by Type:

Non-Conductive Epoxy Die Bonding Adhesive

Electrically Conductive Epoxy Die Bonding Adhesive

Anisotropic Conductive Adhesive

Global Epoxy Die Bonding Adhesive Market, Segmentation by Thermal Conductivity Classification:

Standard Thermal Epoxy Adhesive

High Thermal Conductivity Epoxy Adhesive

Ultra-high Thermal Conductive Epoxy Adhesive

Global Epoxy Die Bonding Adhesive Market, Segmentation by Curing Method:

Thermal Curing Epoxy Adhesive

Fast-curing Epoxy Adhesive

Low-temperature Curing Epoxy Adhesive

Global Epoxy Die Bonding Adhesive Market, Segmentation by Form:

Liquid Epoxy Adhesive

Epoxy Paste Adhesive

Epoxy Adhesive Film

Global Epoxy Die Bonding Adhesive Market, Segmentation by Application:

LED Display and Backlight

Automotive LED

Consumer Electronics LED

Others

Companies Profiled:

Henkel

Dow Chemical

Shin-Etsu Chemical

Darbond

Earlysun Technology

Kmt Technology

Niche-Tech

Huitian Adhesive

NAMICS Corporation

Panacol

Hitachi Chemical(Resonac)

Meridian Adhesive

DELO Industrial Adhesives

Dymax Corporation

Key Questions Answered:

1. How big is the global Epoxy Die Bonding Adhesive market?
2. What is the demand of the global Epoxy Die Bonding Adhesive market?
3. What is the year over year growth of the global Epoxy Die Bonding Adhesive market?
4. What is the production and production value of the global Epoxy Die Bonding Adhesive market?
5. Who are the key producers in the global Epoxy Die Bonding Adhesive market?
6. What are the growth factors driving the market demand?

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